## SN54154, SN74154 4-LINE TO 16-LINE DECODERS/DEMULTIPLEXERS

SDLS056

- '154 is Ideal for High-Performance Memory Decoding
- Decodes 4 Binary-Coded Inputs into One of 16 Mutually Exclusive Outputs
- Performs the Demultiplexing Function by Distributing Data From One Input Line to Any One of 16 Outputs
- Input Clamping Diodes Simplify System
  Design
- High Fan-Out, Low-Impedance, Totem-Pole
  Outputs
- Fully Compatible with Most TTL and MSI Circuits

TYPICAL AVER PROPAGATION D	TYPICAL POWER DISSIPATION	
3 LEVELS OF LOGIC	STROBE	FOWER DISSIPATION
23 ns	19 ns	170 mW

#### description

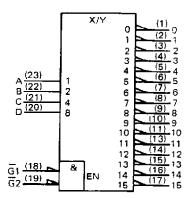
Each of these monolithic, 4-line-to-16-line decoders utilizes TTL circuitry to decode four binary-coded inputs into one of sixteen mutually exclusive outputs when both the strobe inputs,  $\overline{G1}$  and  $\overline{G2}$ , are low. The demultiplexing function is performed by using the 4 input lines to address the output line, passing data from one of the strobe inputs with the other strobe input low. When either strobe input is high, all outputs are high. These demultiplexers are ideally suited for implementing high-performance memory decoders. For ultra-high speed systems, SN54S138/SN74S138 and SN54S139/SN74S139 are recommended.

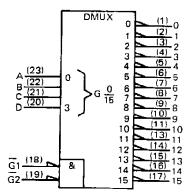
These circuits are fully compatible for use with most other TTL circuits. All inputs are buffered and input clamping diodes are provided to minimize transmissionline effects and thereby simplify system design.

The SN54154 is characterized for operation over the full military temperature range of -55 °C to 125 °C. The SN74154 is characterized for operation from 0 °C to 70 °C.

SN74154.	J OR W PACKAGE N PACKAGE P VIEW)
0 1 1 2 2 3 3 4 4 5 5 6 7 8 9 10 10 11 GND 12	24 VCC 23 A 22 B 21 C 20 D 19 G2 18 G1 17 15 16 14 15 13 14 12 13 11

logic symbols (alternatives)† \_





<sup>1</sup>These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

PRODUCTION DATA documents contain information current as of publication date. Products conform to specifications per the terms of Taxas instruments standard warrenty. Production processing does not necessarily include testing of all parameters.

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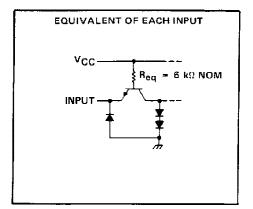
DECEMBER 1972 - REVISED MARCH 88

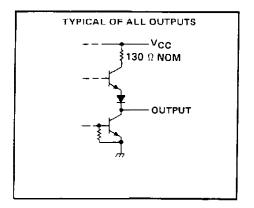
## SN54154, SN74154 **4-LINE TO 16-LINE DECODERS/DEMULTIPLEXERS**

					• •	1			FUN	ICTIO		5LE									
	_	INP	UTS										OUT	PUTS							
Ĝı	ĞΖ	D	<u> </u>	8	<u>A</u>	0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	1!
L	Ł	L	L	L	L	L	н	н	н	н	н	н	н	н	н	н	Ħ	н	н	н	H
L	L	L	L	L	н	н	L	H	н	н	н	н	н	н	н	н	н	н	н	н	-
L	L	L	L	н	L	н	н	L	н	н	н	н	н	н	н	н	н	н	н	н	F
L	L	ι.	I.	н	н	н	н	н	L	н	н	н	н	н	н	н	н	н	н	н	F
L	L	L	н	L	L	н	н	н	н	L	н	н	н	н	н	н	н	н	н	н	H
L	L	L	н	L	Н	н	н	н	н	H	L	н	н	н	н	н	н	н	н	н	۲
L	L	L	н	н	L	н	H	н	н	н	H	L	÷1	н	н	н	н	н	н	н	H
L	L	L	н	н	н	н	н	н	н	н	н	н	L	н	н	н	н	н	н	н	٠
L	L	н	Ļ	L	L	н	н	н	н	н	н	н	Н	L	н	н	н	н	н	н	н
L	L	н	L	L	н	н	н	н	н	н	н	н	н	н	L	н	н	н	н	н	н
L	L	н	L	н	L	ļн.	н	н	н	н	н	н	H	H	H	L	+1	н	н	н	F
Ł	L	н	Ł	н	н	н	н	н	н	н	н	н	н	н	н	н	L	н	н	н	H
L	ι	н	н	L	L	н	н	н	н	н	н	н	н	н	н	н	н	L	н	н	н
L	L	н	н	L	н	н	н	н	н	н	н	н	н	н	н	н	н	н	L	н	н
L	L	н	н	н	L	н	н	н	н	н	н	н	н	н	н	н	н	н	н	L	н
L	L	н	н	Н	н	н	н	н	н	н	н	н	н	н	н	н	н	н	н	н	L
L	н	×	х	Х	×	н	н	Η	н	н	н	н	н	н	н	н	н	н	н	н	н
н	L	×	×	x	×	н	н	н	н	н	н	н	н	н	н	н	н	н	н	н	н
н	н	x	х	х	×	н	н	н	н	н	н	н	н	н	н	н	н	н	н	н	н

H = high level, L = low level, X = Irrelevant

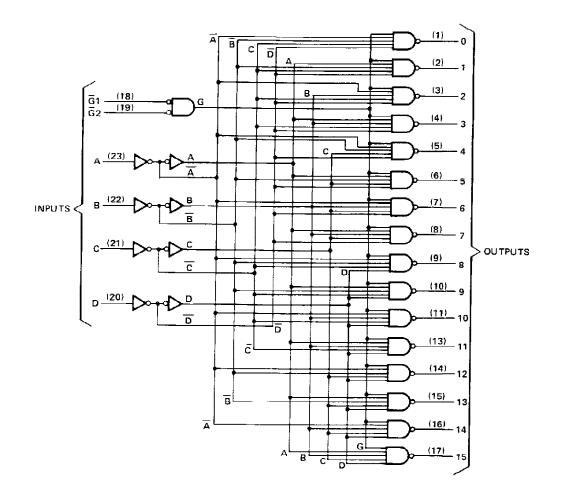
## schematics of inputs and outputs







logic diagram (positive logic)





## SN54154, SN74154 4-LINE TO 16-LINE DECODERS/DEMULTIPLEXERS

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	· · · · · · · · · · · · · · · · · · ·
Operating free-air temperature range: SN54154 Circuits	
SN74154 Circuits	0°C to 70°C
Storage temperature range	

NOTE 1: Voltage values are with respect to network ground terminal.

#### recommended operating conditions

		SN5415	4				
	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V <sub>CC</sub>	4.5	5	5.5	4.75	5	5.25	V
High-level output current, IOH			-800			800	μA
Low-level output current, IOL			16			16	mA
Operating free-air temperature, T <sub>A</sub>	-55		125	0		70	С

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		TERT CONDUCTION		SN5415	54	SN74154				
	PARAMETER	TEST CONDITIONS <sup>†</sup>	MIN	түр	MAX	MIN	TYP‡	MAX		
VIH	High-level input voltage		2			2			V	
VIL	Low-level input voltage				0.8			0.8	V	
VIK	Input clamp voltage	$V_{CC} = MIN$ , $I_I = -12 \text{ mA}$			-1.5			-1.5	V	
v <sub>oн</sub>	High-level output voltage	V <sub>CC</sub> = MIN. V <sub>IH</sub> = 2 V. V <sub>IL</sub> = 0.8 V, I <sub>OH</sub> = -800 µA	2.4	3.4		2.4	3.4		v	
VOL	Low-level output voltage	V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V, V <sub>IL</sub> = 0.8 V, I <sub>OL</sub> = 16 mA		0.2	0.4		0.2	0.4	v	
1 <sub>1</sub>	Input current at maximum input voltage	V <sub>CC</sub> = MAX, VI = 5.5 V	1		1			1	mΑ	
łн	High-level input current	V <sub>CC</sub> = MAX, V <sub>1</sub> = 2.4 V			40			40	μA	
4L	Low-level input current	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0.4 V	T		-1.6			-1.6	mA	
los	Short-circuit output current §	V <sub>CC</sub> = MAX	-20		-55	~18		-57	mΑ	
Icc	Supply current	V <sub>CC</sub> = MAX, See Note 2		34	49		34	56	mА	

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type. <sup>‡</sup>All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25 °C.

\$ Not more than one output should be shorted at a time,

NOTE 2: ICC is measured with all inputs grounded and all outputs open.

#### switching characteristics, VCC = 5 V, TA = 25°C

[	PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT
tpl.H	Propagation delay time, low-to-high-level output, from A, B, C, or D inputs through 3 levels of logic				24	36	пs
<sup>t</sup> PHL	Propagation delay time, high-to-low-level output, from A, B, C, or D inputs through 3 levels of logic	 CL-15pF, RL-400Ω	,		22	33	ns
t <b>P</b> LH	Propagation delay time, low-to-high-level output, from either strobe input	See Note 3			20	30	17\$
TPHL	Propagation delay time, high-to-low-level output, from either strobe input				18	27	пs

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.





25-Sep-2013

# **PACKAGING INFORMATION**

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9558101QJA	ACTIVE	CDIP	J	24	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	5962-9558101QJ A SNJ54154J	Samples
5962-9558101QKA	ACTIVE	CFP	W	24	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9558101QK A SNJ54154W	Samples
5962-9558101QKA	ACTIVE	CFP	W	24	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9558101QK A SNJ54154W	Samples
SN54154J	ACTIVE	CDIP	J	24	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	SN54154J	Samples
SN54154J	ACTIVE	CDIP	J	24	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	SN54154J	Samples
SN74154DW	OBSOLETE	SOIC	DW	24		TBD	Call TI	Call TI	0 to 70		
SN74154DW	OBSOLETE	SOIC	DW	24		TBD	Call TI	Call TI	0 to 70		
SN74154N	ACTIVE	PDIP	Ν	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74154N	Samples
SN74154N	ACTIVE	PDIP	N	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74154N	Samples
SN74154N3	OBSOLETE	PDIP	Ν	24		TBD	Call TI	Call TI	0 to 70		
SN74154N3	OBSOLETE	PDIP	Ν	24		TBD	Call TI	Call TI	0 to 70		
SN74154NE4	ACTIVE	PDIP	Ν	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74154N	Samples
SN74154NE4	ACTIVE	PDIP	Ν	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74154N	Samples
SNJ54154J	ACTIVE	CDIP	J	24	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	5962-9558101QJ A SNJ54154J	Samples
SNJ54154J	ACTIVE	CDIP	J	24	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	5962-9558101QJ A SNJ54154J	Samples
SNJ54154W	ACTIVE	CFP	W	24	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9558101QK A SNJ54154W	Samples
SNJ54154W	ACTIVE	CFP	W	24	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9558101QK	Samples



25-Sep-2013

Orderable Device	Status	Package Type	•	Pins	•	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)		(3)		(4/5)	
					_		-		-	A	_
										SNJ54154W	

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between

the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(<sup>5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

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#### OTHER QUALIFIED VERSIONS OF SN54154, SN74154 :

Catalog: SN74154



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# PACKAGE OPTION ADDENDUM

25-Sep-2013

Military: SN54154

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

# **MECHANICAL DATA**

MCDI004A - JANUARY 1995 - REVISED NOVEMBER 1997

### **CERAMIC DUAL-IN-LINE PACKAGE**

J (R-GDIP-T\*\*)



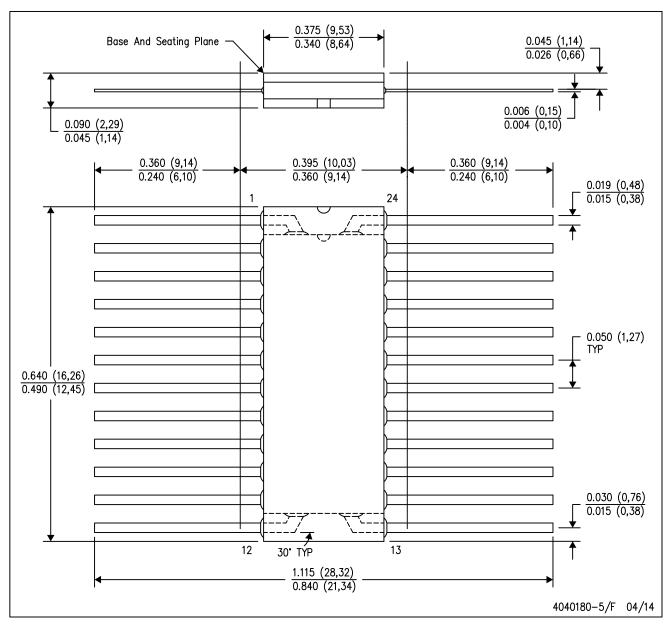
NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Window (lens) added to this group of packages (24-, 28-, 32-, 40-pin).
- D. This package can be hermetically sealed with a ceramic lid using glass frit.
- E. Index point is provided on cap for terminal identification.



CERAMIC DUAL FLATPACK

W (R-GDFP-F24)



NOTES: A. All linear dimensions are in inches (millimeters).

- This drawing is subject to change without notice. В.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
  E. Falls within Mil-Std 1835 GDFP2-F20



# **MECHANICAL DATA**

MPDI008 - OCTOBER 1994

## N (R-PDIP-T\*\*)

### PLASTIC DUAL-IN-LINE PACKAGE

24 PIN SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-011
- D. Falls within JEDEC MS-015 (32 pin only)



DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013 variation AD.



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